



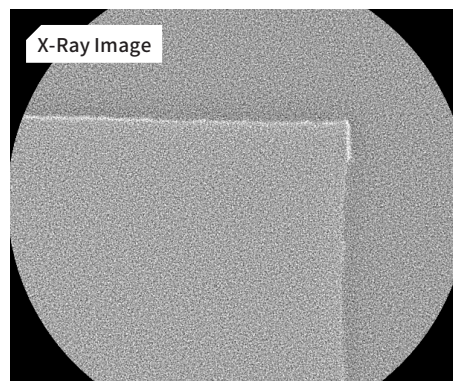
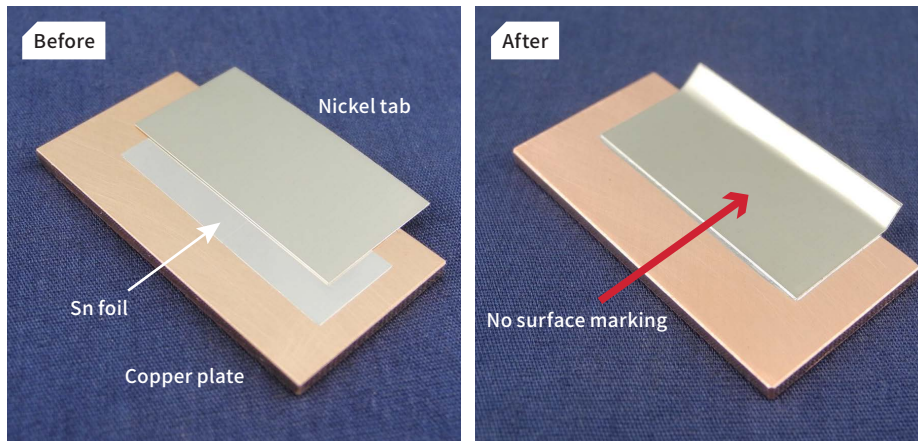
Patented

Application

Bonding

Nickel Tab and Copper Plate

Clean, Void-free Alloy Bonding



System Used

15MZs



AP-E-0041A4-2026063001